

S/N 10/723,474



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Suan J. Boon	Examiner:	DiLinh Nguyen
Serial No.:	10/723,474	Group Art Unit:	2814
Filed:	November 26, 2003	Docket:	303.601US2
Title:	ELECTRONIC APPARATUS HAVING AN ADHESIVE LAYER FROM WAFER LEVEL PACKAGING		

INFORMATION DISCLOSURE STATEMENT

MS RCE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant requests that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicant with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

INFORMATION DISCLOSURE STATEMENT

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Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications, and Non-Published Applications identifiable by USPTO Serial Number, are no longer required to be provided to the Office. Notification of this change to this effect was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004 and October 19, 2004. Thus, Applicant has not included copies of any US Patents or US Patent Applications identifiable by serial number that may be cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

SUAN J. BOON

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
612-373-6900

Date AUGUST 31, 2006

By Robert Madden
Robert Madden
Reg. No. 57,521

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop RCE, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 31 day of August 2006.

Steve Cannon
Name

Steve Cannon
Signature



N 10/723,474

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Examiner: DiLinh Nguyen
Group Art Unit: 2814
Docket: 303.601US2

COMMUNICATION CONCERNING RELATED APPLICATION(S)**MS RCE**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicant would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date/Issue Date</u>	<u>Attorney Docket</u>	<u>Title</u>
11460089	July 26, 2006	303.601US4	WAFER LEVEL PRE-PACKAGED FLIP CHIP
11460093	July 26, 2006	303.601US5	WAFER LEVEL PRE-PACKAGED FLIP CHIP
11460435	July 27, 2006	303.601US6	WAFER LEVEL PRE-PACKAGED FLIP CHIP SYSTEMS
11460445	July 27, 2006	303.601US7	WAFER LEVEL PRE-PACKAGED FLIP CHIP SYSTEM

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,
SUAN J. BOON
By Applicant's Representatives,
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
612-373-6900

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By

Robert Madden
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KATE GAMM
Name

Kate Gamm
Signature



Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)

Complete if Known

Application Number	10/723,474
Filing Date	November 26, 2003
First Named Inventor	Boon, Suan
Group Art Unit	2814
Examiner Name	Nguyen, DiLinh

Sheet 1 of 1

Attorney Docket No: 303.601US2

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate
	US-5,849,608	12/15/1998	Abe, M.	05/29/1997
	US-6,063,646	05/16/2000	Okuno, A. , et al.	10/06/1998
	US-6,103,552	08/15/2000	Lin, Mou-Shiung	08/10/1998
	US-6,177,296	01/23/2001	Vindasius, A. , et al.	03/22/1999
	US-6,492,200	12/10/2002	Park, I. S., et al.	05/24/1999
	US-6,903,451	06/07/2005	Kim, N. S., et al.	11/27/2000

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T ²
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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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EXAMINER**DATE CONSIDERED**

Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹ Applicant's unique citation designation number (optional) ² Applicant is to place a check mark here if English language Translation is attached